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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/648,237	08/27/2003	Chaur-Chin Yang	BHT-3183-53	3764

7590 09/06/2005
BRUCE H. TROXELL
SUITE 1404
5205 LEESBURG PIKE
FALLS CHURCH, VA 22041

EXAMINER

ROSE, KIESHA L

ART UNIT	PAPER NUMBER
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2822

DATE MAILED: 09/06/2005

Please find below and/or attached an Office communication concerning this application or proceeding.

JP

Office Action Summary	Application No.	Applicant(s)	
	10/648,237	YANG ET AL.	
	Examiner	Art Unit	
	Kiesha L. Rose	2822	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 18 July 2005.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 25-38 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 25-38 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1:121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|---|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413) |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | Paper No(s)/Mail Date. _____ |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| Paper No(s)/Mail Date _____ | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

This Office Action is in response to the RCE filed 18 July 2005.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 25-28,33-34 and 36-37 are rejected under 35 U.S.C. 103(a) as being unpatentable over Giri et al. (U.S. Patent 6,765,152) in view of Ahn et al. (U.S. Patent 6,424,034).

Giri discloses a chip module (Figs. 1-4) that contain a substrate (12) (printed circuit board) having a top surface, bottom surface and a substrate opening extending through the top surface and the bottom surface, a dummy die (18) (interposer) connected to the bottom surface and aligned with the substrate opening, wherein the dummy die has a redistribution layer electrically connected with the substrate having flip chip pads and connecting pads connected by a trace on the top surface of the dummy die, a chip (22) located in the opening and having a plurality of bumps electrically connected with the flip chip pads of the redistribution layer where the dummy die is larger than the chip, packaging (34) located in the substrate opening and encasing the chip, a plurality of top connection pads located on the top substrate surface, solder balls

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(14) formed on the bottom surface of the substrate and the dummy die has an exposed surface located on the bottom surface and has a metal thermal conducting layer (layer on the underside of the dummy die where the other chips are formed) and adhesive tape can be used to connect the dummy die to the bottom substrate surface. (Fig. 3) Giri discloses all the limitations except for the dummy die to be a silicon substrate having no electrically calculating function. Whereas Ahn discloses a microprocessor (Fig. 2) that contains a dummy die (interposer), which is a silicon substrate with no electrically calculating function, a die (120) and a redistribution layer (140) on the dummy die. The dummy die is a silicon substrate (interposer) with no electrically calculating function which is formed to carry both memory chips and microprocessors and connect the chips and microprocessor through the holes that extend through the dummy die (silicon substrate). Therefore it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the device of Giri by incorporating the dummy die to be a silicon substrate with no electrically calculating function to carry both memory chips and microprocessors and electrically connect the chips and microprocessor through the holes that extend through the dummy die (silicon substrate) as taught by Ahn.

Claims 29-30 and 35 are rejected under 35 U.S.C. 103(a) as being unpatentable over Giri and Ahn in view of Klein et al. (U.S. Publication 2004/0145051).

Giri and Ahn disclose all the limitations except for stacked semiconductor package and pitch size for the flip chip pads. Whereas Klein discloses a semiconductor package (Fig. 9a) that contains a die (12) with a redistribution layer formed thereon with

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flip chip pads (22) and connecting pads where the flip chip pads have a smaller pitch than the connecting pads and a plurality of stacked semiconductor packages including a plurality of outer terminals (118) connecting the connection pads (52). The package is a stacked semiconductor package in order to form a system. (Page 7, Paragraph 96)

Therefore it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the devices of Giri and Ahn by incorporating a stacked semiconductor package to create a system for electrical connection as taught by Klein. In regards to claims 29 and 30, it would have been obvious to one having ordinary skill in the art at the time the invention was made to have the pitch of the flip chip being 150 μ m, since it has been held that discovering the optimum value of a result effective variable involves only routine skill in the art. In re Boesch, 617 F. 2d 272, 205 USPQ 215 (1980).

Claim 31 is rejected under 35 U.S.C. 103(a) as being unpatentable over Giri and Ahn in view of Kikuma et al. (U.S. Patent 6,621,169).

Giri and Ahn disclose all the claimed limitations except for bonding wires connecting the redistribution layer to the substrate. Whereas Kikuma discloses a stacked semiconductor device (Fig. 25) that contains a substrate (108) and a chip with a redistribution layer (114) formed thereon where the redistribution layer and substrate are connected by bonding wires (116). The substrate and redistribution layer are connected by bonding wires to form an electrical connection between the two. (Column 17, lines 60-64) Therefore it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the devices of Giri and Ahn by

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incorporating the redistribution layer and substrate to be connected by bonding wires to form an electrical connection between the two as taught by Kikuma.

Claim 32 is rejected under 35 U.S.C. 103(a) as being unpatentable over Giri and Ahn in view of Koopmans (U.S. Publications 2004/0035840).

Giri and Ahn disclose all the limitations except for bumps bonding the connecting pads of the redistribution layer to the substrate. Whereas Koopmans discloses a flip chip (Fig. 1a) that contains a substrate (34) and a redistribution layer (21) with connecting pads (20) and bumps (26) that bond the connecting pads of the redistribution layer to the substrate. The bumps are formed between the connecting pads of the redistribution layer and the substrate to enable electrical interconnection to a package (redistribution layer and substrate). (Page 1, Paragraph 7) Therefore it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the devices of Giri and Ahn by incorporating bumps between the connecting pads of the redistribution layer and the substrate to enable electrical interconnection to a package (redistribution layer and substrate) as taught by Koopmans.

Claim 38 is rejected under 35 U.S.C. 103(a) as being unpatentable over Giri and Ahn in view of Higgins III (U.S. Patent 5,583,377).

Giri and Ahn disclose all the claimed limitations except for the substrate to have a stair configuration. Whereas Higgins discloses a semiconductor device (Fig. 2) that contains a substrate (42) with a stair configuration (44) and a chip (13) mounted in the opening of the substrate. The substrate is formed with a stair configuration to help with

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the manufacturing cost and form a lower profile device. (Column 5, lines 18-20)

Therefore it would have been obvious to one having ordinary skill in the art at the time the invention was made to modify the devices of Giri and Ahn by incorporating the substrate to have a stair configuration to help with manufacturing cost and make a lower profile device as taught by Higgins.

Response to Arguments

Applicant's arguments with respect to claims 25-38 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Kiesha L. Rose whose telephone number is 571-272-1844. The examiner can normally be reached on M-F 8:30-6:00 off 2nd Mondays.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Amir Zarabian can be reached on 571-272-1852. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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KLR


AMIR ZARABIAN
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